IS80C52/32 CMOS SINGLE CHIP 8-BIT MICROCONTROLLER



ADVANCE INFORMATION ARPIL 1997

FEATURES

- 8K x 8 ROM (IS80C52 only)
- 256 x 8 RAM
- Three 16-bit timers/counters
- Full duplex serial channel
- · Boolean processor
- Four 8-bit I/O ports, 32 I/O lines
- External memory expandable to 128K
- · Two security bits
- CMOS and TTL compatible
- Maximum speed range: 40 MHz @ Vcc = 5V
 - Packages available:
 - 40-pin DIP
 - 44-pin PLCC
 - 44-pin PQFP

GENERAL DESCRIPTION

The ISSI IS80C52/32 is a high-performance microcontroller fabricated using high-density CMOS technology. The CMOS IS80C52/32 is functionally compatible with the NMOS Intel 8052/32 microcontroller.

The IS80C52 is designed with 8K x 8 ROM; 256 x 8 RAM; 32 I/O lines for either multiprocessor communications, I/O expansion, or full duplex UART; three 16-bit timers/counters; a five-source, two-priority-level, nested interrupt structure; and an on-chip oscillator and clock circuit. The IS80C52 can be expanded using standard TTL compatible memory.



Figure 1. IS80C52/32 Pin Configurations

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Figure 1. IS80C52/32 Pin Configurations (continued)





PIN DESCRIPTION

Symbol	DIP	PLCC	QFP	I/O	Name and Function
P1.0-P1.7	1-8	2-9	40-44	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pullups. Port 1 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pullups.
RST	9	10	4	I	Reset: A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to GND permits a power-on reset using only an external capacitor. A small internal resistor permits power-on reset using only a capacitor connected to VCC.
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pullups. Port 3 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pullups.
	10 11 12 13	11 13 14 15	5 7 8 9	 0 	Port 3 also serves the special features of the IS80C52, as listed below: RxD (P3.0): Serial input port TxD (P3.1): Serial output port INTO (P3.2): External interrupt INT1 (P3.3): External interrupt
	14 15 16 17	16 17 18 19	10 11 12 13	 0 0	T0 (P3.4): Timer 0 external input T1 (P3.5): Timer 1 external input WR (P3.6): External data memory write strobe RD (P3.7): External data memory read strobe
XTAL 2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier.
XTAL 1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
GND	20	22	16	Ι	Ground: 0V reference.
P2.0-P2.7	21-28	24-31	18-25	I/O	Port 2: Port 2 is an 8-bit bi-directional I/O port with internal pullups. Port 2 pins that have 1s written to them are pulled high by the internal pullups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pullups. Port 2 emits the high order address byte during fetches from external program memory and during accesses to external data memory that used 16-bit addresses. In this application, it uses strong internal pullups when emitting 1s. During accesses to external data memory that use 8-bit addresses, Port 2 emits the contents of the P2 special function register.

(continued)

PIN DESCRIPTION (continued)

Pin Symbol	DIP	PLCC	QFP	I/O	Name and Function
PSEN	29	32	26	0	Program Store Enable: The read strobe to external program memory. When the device is executing code from the external program memory, <u>PSEN</u> is activated twice each machine cycle except that two <u>PSEN</u> activations are skipped during each access to external data memory. <u>PSEN</u> is not activated during fetches from internal program memory.
ALE	30	33	27	I/O	Address Latch Enable: Output pulse for latching the low byte of the address during an address to the external memory. In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency, and be used for external timing or clocking. Note that one ALE pulse is skipped during each access external data memory.
ĒĀ	31	35	29	I	External Access enable: EA must be externally held low to enable the device to fetch code from external program memory locations 0000H to 0FFFH. If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 0FFFH.
P0.0-P0.7	39-32	43-36	30-37	I/O	Port 0: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pullups when emitting 1s.
Vcc	40	44	38	I	Power Supply: This is the power supply voltage for operation.

OPERATING DESCRIPTION

The detail description of the IS80C52 included in this description are:

- Memory map and registers
- Timers/counters
- Serial interface
- Interrupt system
- Instruction
- Other information

Memory Map and Registers

Memory

The IS80C52 has separate address spaces for program and data memory. The program memory can be up 64K bytes long. The lower 4K can reside onchip. Figure 3 shows a map of the IS80C52 program memory.

The IS80C52 has 256 bytes of on-chip RAM, plus a number of special function registers. The lower 128 bytes can be accessed either by direct addressing or by indirect addressing. Figure 4 shows data memory origination.

The 128 bytes of RAM which can be accessed by both direct and indirect addressing can be divided into three segments as listed below and shown in Figure 5.

- 1. *Register Banks 0-3:* locations 0 through 1FH (32 bytes). The device after reset defaults to register bank 0. To use the other register banks, the user must select them in software. Each register bank contains eight 1-byte registers 0-7. Reset initializes the stack point to location 07H, and is incremented once to start from 08H, which is the first register of the second bank.
- 2. *Bit Addressable Area:* 16 bytes have been assigned for this segment 20H-2FH. Each one of the 128 bits of this segment can be directly addressed (0-7FH). The bits can be referred to in two ways, both of which are acceptable by most assemblers. One way is referencing to bytes 20H-2FH. Thus, bits 0-7 can also be referred to as bits 20.0-20.7, and bits 8-FH are the same as 21.0-21.7, and so on. Each of the 16 bytes in this segment can also be addressed as a byte.
- 3. *Scratch Pad Area:* 30-7FH are available to the user as data RAM. However, if the data pointer has been initialized to this area, enough bytes should be left aside to prevent SP data destruction.



Figure 3. Program Memory Access Range



Figure 4. Data Memory Access Range



Figure 5. 128 Bytes of RAM Direct and Indirect Addressable

SPECIAL FUNCTION REGISTER

Symbol	Description	Direct Address	Bit Address, Symbol, or Alternative Port Function							Reset Value	
ACC ⁽¹⁾	Accumulator	E0H	E7	E6	E5	E4	E3	E2	E1	E0	00H
B ⁽¹⁾	B register	F0H	F7	F6	F5	F4	F3	F2	F1	F0	00H
DPH	Data pointer high	83H									00H
DPL	Data pointer low	82H									00H
IE ⁽¹⁾	Interrupt enable	A8H	AF EA	AE 	AD —	AC ES	AB ET1	AA EX1	A9 ET0	A8 EX0	0X000000B
	Interrupt priority	B8H	BF —	BE —	BD —	BC PS	BB PT1	BA PX1	B9 PT0	B8 PX0	XXX00000B
P0 ⁽¹⁾	Port 0	80H	87 P0.7	86 P0.6	85 P0.5	84 P0.4	83 P0.3	82 P0.2	81 P0.1	80 P0.0	FFH
P1 ⁽¹⁾	Port 1	90H	97 P1.7	96 P1.6	95 P1.5	94 P1.4	93 P1.3	92 P1.2	91 P1.1	90 P1.0	FFH
P2 ⁽¹⁾	Port 2	A0H	A7 P2.7	A6 P2.6	A5 P2.5	A4 P2.4	A3 P2.3	A2 P2.2	A1 P2.1	A0 P2.0	FFH
P3 ⁽¹⁾	Port 3	B0H	B7 P3.7	B6 P3.6	B5 P3.5	B4 P3.4	B3 P3.3	B2 P3.2	B1 P3.1	B0 P3.0	FFH
PCON	Power control	87H	SMO) —	—	_	GF1	GF0	PD	IDL	0XXX0000B
PSW ⁽¹⁾	Program status word	D0H	D7 CY	D6 AC	D5 F0	D4 RS1	D3 RS0	D2 OV	D1 —	D0 P	00H
SBUF	Serial data buffer	99H									XXXXXXXXB
SCON ⁽¹⁾	Serial controller	98H	9F SM0	9E SM1	9D SM2	9C Ren	9B TB8	9A RB8	99 Ti	98 RI	00H
SP	Stack pointer	81H									07H
TCON ⁽¹⁾	Timer control	88H	8F TF1	8E TR1	8D TF0	8C TR0	8B IE1	8A IT1	89 IE0	88 IT0	
TH0	Timer high 0	8CH									00H
TH1	Timer high 1	8DH									00H
TL0	Timer low 0	8AH									00H
TL1	Timer low 1	8BH									00H
TMOD	Timer mode	89H	GATE	C/T	M1	MO	GATE	C/T	M1	M0	00H

Note:

1. Denotes bit addressable.

The detail description of each bit is as follows:

PSW

CY	AC F	0 RS1 RS0 OV — P						
CY	PSW.7	Carry flag						
AC	PSW.6	Auxiliary carry flag						
F0	PSW.5	Flag 0 available to the user for general purpose						
RS1	PSW.4	Register bank selector bit 1						
RS0	PSW.3	Register bank selector bit 0 ⁽¹⁾						
OV	PSW.2	Overflow flag						
	PSW.1	Usable as a general purpose flag						
Ρ	PSW.0	Parity flag. Set/clear by hardware each instruction cycle to indicate an odd/even number of "1" bus in the accumulator						

Note:

1. The value presented by RS0 and RS1 selects the corresponding register bank.

RS1	RS0	Register Bank	Address
0	0	0	00H-07H
0	1	1	08H-0FH
1	0	2	10H-17H
1	1	3	18H-1FH

PCON

SMOD	_	—	—	GF1	GF0	PD	IDL
SMOD	Dou gen rate in n	uble b lerate e is do nodes	baud ra baud ubled s 1, 2,	ate bit. rate and when th or 3.	If Timer d SMOD he seria	1 is u)=1, th I port i	ised to ebaud is used

- Not implemented, reserve for future use.
- Not implemented, reserve for future use.
- Not implemented, reserve for future use.
- GF1 General purpose flag bit.
- GF0 General purpose flag bit.
- PD Power-down bit. Setting this bit activates power-down operation in the IS80C52.
- IDL Idle mode bit. Setting this bit activates idle mode operation in the IS80C52. If 1s are written to PD and IDL at the same time, PD takes precedence.

IE

EA	_	— ES ET1 EX1 ET0 EX0
EA	IE.7	Disable all interrupts. If EA=0, no interrupt will be acknowledged. If EA=1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
	IE.6	Not implemented, reserve for future use.
	IE.5	Not implemented, reserve for future use.
ES	IE.4	Enable or disable the serial port interrupt.
ET1	IE.3	Enable or disable the timer 1 overflow interrupt.
EX1	IE.2	Enable or disable external interrupt 1.
ET0	IE.1	Enable or disable the timer 0 overflow interrupt.
EX0	IE.0	Enable or disable external interrupt 0.

IP

_	_	- PS PT1 PX1 PT0 PX0
	IP.7	Not implemented, reserve for future use.
—	IP.6	Not implemented, reserve for future use.
	IP.5	Not implemented, reserve for future use.
PS	IP.4	Defines the serial port interrupt priority level.
PT1	IP.3	Defines the timer 1 interrupt priority level.
PX1	IP.2	Defines the external interrupt 1 priority level
PT0	IP.1	Defines the timer 0 interrupt priority level.
PX0	IP.0	Defines the external interrupt 0 priority level

TCON

TF1	TR1 TF0	TR0	IE1	IT1	IE0	IT0
TF1	TCON.7	Timer hardwar overflov process service	1 ove rewhe vs.Cle or vec routine	rflow fl n the tim ared by tors to e.	ag. S er/cou hardw the int	et by inter 1 are as errupt
TR1	TCON.6	Timer 1 by softw ON/OFF	run co /are to =.	ntrol bit. turn tim	Set/cl er/cou	eared Inter 1
TF0	TCON.5	Timer hardwar overflow process service	0 ove rewhe vs.Clea or vec routine	rflow fl n the tim ared by stors to t e.	ag. S ier/cou hardw the int	et by inter0 areas errupt
TR0	TCON.4	Timer 0 by softw ON/OFF	run co /are to - .	ntrol bit. turn tim	Set/cl er/cou	leared Inter 0
IE1	TCON.3	Externa by softw edge is hardwa process	l interr are wh s dete tre w ed.	upt 1 eo len exter ected. (hen ir	dge fla rnal int Cleare nterru	g. Set errupt ed by pt is
IT1	TCON.2	Interrup cleared edge/lov interrup	t 1 ty∣ by sof w leve t.	pe cont tware sj I trigge	rol bit becify red ex	. Set/ falling tternal
IE0	TCON.1	Externa by softw edge is hardwa process	l interr are wh s dete tre w ed.	upt 0 ec en exter ected. (hen ir	dge fla rnal int Cleare nterru	g. Set errupt ed by pt is
IT0	TCON.0 In	terrupt0 by softv	type.co vare s	ontrol bit pecify f	. Set/c alling	leared edge/

110 ICON.0 Interrupt 0 type control bit. Set/cleared by software specify falling edge/ low level triggered external interrupt.

TMOD

Timer 1	Timer 0		
GATE C/T M1 M0	GATE C/T	M1	MO

- GATE When TRx (in TCON) is set and GATE=1, TIMER/COUNTERx will run only while INTx pin is high (hardware control). When GATE=0, TIMER/COUNTERx will run only while TRx=1 (software control).
- C/T Timer or counter selector. Cleared for timer operation (input from internal system clock). Set for counter operation (input from Tx input pin).
- M1 Mode selector bit.⁽²⁾
- M0 Mode selector bit.⁽²⁾

Note 2:

M1	MO	Operating mode
0	0	Mode 0. (13-bit timer)
0	1	Mode 1. (16-bit timer/counter)
1	0	Mode 2. (8-bit auto-load timer/counter)
1	1	Mode 3. (TL0 is an 8-bit timer/counter controller by the standard timer 0 control bits. TH0 is an 8-bit timer and is controlled by timer 1 controller bits.)
1	1	Mode 3. (Timer/counter 1 stopped).

SCON

SM0	SM1 SM2	2 REN	TB8	RB8	TI	RI
SM0	SCON.7	Serial po	ort mod	de spec	ifier. ⁽³⁾	
SM1	SCON.6	Serial po	ort moo	de spec	ifier. ⁽³⁾	
SM2	SCON.5	Enable municati 3. In moo then RI received mode 1, i activated receive. be 0.	the m on fea de 2 or will no 9th da if SM2 d if val In mo	ultiproc ture in 3, if SM t be act ata bit (=1 then lid stop ode 0, 5	essor mode M2 is s tivatec RB8) i RI will bit wa SM2 s	com- 2 and et to 1 I if the s 0. In not be as not should
REN	SCON.4	Set/clear disable r	red by ecepti	softwai on.	re to e	nable/
TB8	SCON.3	The 9th in mode software	bit tha 2 and	t will be d 3. Se	trans t/clear	mitted ed by
RB8	SCON.2	In mode data bit ti 1, if SM2 was rece not used	s 2 an hat wa e=0, RI eived. I.	d 3, RE s receiv 38 is the In mod	38 is tl ved. In estop I le 0, F	he 9th mode oit that RB8 is
ΤI	SCON.1	Transmi hardward time in m of the sto Must be	t inte e at th node 0 op bit cleare	rrupt fl e end o , or at th in the o ed by so	ag. S f the ne beg ther m ftware	Set by 8th bit inning nodes. e.
RI	SCON.0	Receive hardward time in m the stop l (except s by softward	inter e at th node 0 bit time see SM are.	rupt fl. e end c , or half e in the (12). Mus	ag. S of the way th other r st be c	et by 8th bit rough nodes leared
NOLE	э.					

SM0	SM1	MODE	Description	Baud rate
0	0	0	Shift register	Fosc/12
0	1	1	8-bit UART	Variable
1	0	2	9-bit UART	Fosc/64 or Fosc/32
1	1	3	9-bit UART	Variable

Timers/counters

The IS80C52 contains two 16-bit counters for measuring time intervals, measuring pulse widths, counting events and generating precise, periodic interrupt request.

The operating mode is listed below.

Timer 1/Counter 1:

Timer 1/Counter 1 can be configured in one of four modes:

- Mode 0: Provides an 8-bit counter with a divideby-32 prescaler or an 8-bit timer with a divide-by-32 prescaler. A read/write of TH1 accesses counter 1's bits 12-5. A read/write of TL1 accesses counter 1's bits 7-0. TL1 bits 4-0 are the prescaler (counter 1's 4-0) while bits 7-5 are indeterminate and should be ignored. The programmer should clear the prescaler (counter 1's bits 4-0) before setting the run flag.
- Mode 1: Configures counter 1 as a 16-bit timer/ counter.
- Mode 2: Configures counter 1 as an 8-bit autoreload value. TH1 holds the reload value. TL1 is incremented. The value in TH1 is reload onto TL1 when TL1 overflows from all ones.
- Mode 3: When counter 1's mode is repro-grammed to mode 3 (from mode 0, 1 or 2), it disables the incrementing of the counter. This mode is provided as an alternative to use TR1 bit (TCON.6) to start and stop counter 1.

The serial port receives a pulse each time that counter 1 overflows. The standard UART mode divides this pulse rate to generate the transmission rate.

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Counter 0/ Timer 0:

Counter 0 can also be configured in one of four modes:

- Mode 0-2: Mode 0-2 are the same as for counter 1.
- Mode 3: In mode 3, the configure of TH0 is not affected by the bits in TMOD or TCON. It is configured solely as an 8-bit timer that is enabled for incrementing by TCON's TR1 bit. Upon TH0's overflow the TF1 flag gets set. Thus, neither TR1 nor TF1 is available to counter 1 when counter 0 is in mode 3. The function of

TR1 can be done by placing counter 1 in mode 3, so only the function of TF1 is actually given up by counter 1. In mode 3, TL0 is configured as an 8-bit timer/counter and is controlled, as usual, by the GATE (TMOD. 3), C/ (TMOD.2), TR0 (TCON.4) and TF0 (TCON.5) control bits.

The use of the timers/counters is determined by two 8-bit registers, TMOD and TCON is shown in SFR. The counter input circuit is shown in Figures 6 and 7.



Figure 6. Timer/event Counter 0 Control and Status Flag Circiut



Figure 7. Timer/event Counter 1 Control and Status Flag Circiut

Serial Interface

The IS80C52 has a serial I/O port that is useful for serial linking peripheral devices as well as multiple IS80C52s through standard asynchronous protocol with full-duplex operations. The data for transmission to and from reception reside in the serial port buffer register (SBUF). The serial port control and the monitoring of its status is provided by the serial port control register (SCON). The contents of the 8-bit SCON register are shown in SFR.

The IS80C52 has a serial channel useful for serially linking UART (universal asynchronous receiver/ transmitter) devices and for expanding I/O. The full-

duplex serial I/O port can be programmed to function in one of four operating modes:

Mode 0:	Synchronous I/O expansion using TTL
	or CMOS shift registers.

- Mode 1: UART interface with 10-bit frame and variable transmission rate.
- Mode 2: UART interface with 11-bit frame and fixed transmission rate.
- Mode 3: UART interface with 11-bit frame and variable transmission rate.

The serial interface circuit is shown in Figures 8 and 9. The use of the serial interface is determined by TCON and PCON registers is shown in SFR.



Figure 8. Serial Port: Synchronous Mode 0



Figure 9. Serial Port: UART Mode 1, 2, and 3

Interrupt System

External events and the real-time driven on-chip peripherals require service by the CPU asynchronous to the execution of any particular section code. To tie the asynchronous activities of these functions to normal program execution, a sophisticated multiplesource, two-priority-level, nested interrupt system is provided. The interrupt system is shown in Figure 10. The interrupt request flag and program memory location of interrupt service program is shown in the table below:

Interrupt Source	Request Flag	Bit Location	Start Address	
External Request 0	IE0	TCON.1	3 (0003H)	
Internal Timer 0/Counter 0	TF0	TCON.5	11 (000BH)	
External Request 1	IE1	TCON.3	19 (0013H)	
Internal Timer 1/Counter 1	TF1	TCON.7	27 (001BH)	
Internal Serial Port (XMIT)	TI	SCON.1	35 (0023H)	
Internal Serial Port (RCVR)	RI	SCON.0	35 (0023H)	



Figure 10. Interrupt System

ADDITIONAL INFORMATION

Idle mode

In idle mode, the CPU puts itself to sleep while all the on-chip perpherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the Special Function Register remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

It should be noted that when idle is terminated by a hardware reset, the device normally resumes program exection, from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle is terminated by reset, the instruction following the one that invokes idle should not be one that writes to a port pin or to external memory. The status of external pins is shown in the following table.

Power-down mode

In the power-down mode the oscillator is stopped, and the instruction that invokes power down is the last instruction executed. The on-chip RAM and special function register retain their values until the power down mode is terminated.

The only exit from power-down mode is a hardware reset. Reset redefines the SFR but does not change the on-chip RAM. The reset should not be activated before VCC is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize. The status of the external pins during idle and power-down mode is shown in the following table.

Mode	Memory	ALE	PSEN	PORT 0	PORT 1	PORT 2	PORT 3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Status of the External Pins during Idle and Power-down modes.

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ROM Verification

The address of the program memory location to be read is applied to Port 1 and pins P2.3-P2.0. The other pins should be held at the "Verify" level are indicated in Figure 11. The contents of the addressed locations exits on Port 0. External pullups are required on Port 0 for this operation. Figure 11 shows the setup to verify the program memory.



Figure 11. ROM Verification

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Parameter	Value	Unit
VTERM	Terminal Voltage with Respect to GND ⁽²⁾	-2.0 to +7.0	V
TBIAS	Temperature Under Bias ⁽³⁾	0 to +70	°C
Tstg	Storage Temperature	-65 to +125	°C
Рт	Power Dissipation	1.5	W

Note:

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

 Minimum DC input voltage is -0.5V. During transitions, inputs may undershoot to -2.0V for periods less than 20 ns. Maximum DC voltage on output pins is Vcc + 0.5V which may overshoot to Vcc + 2.0V for periods less than 20 ns.

3. Operating temperature is for commercial products only defined by this specification.

OPERATING RANGE⁽¹⁾

Range	Ambient Temperature	Vcc	Oscillator Frequency	
Commercial	0°C to +70°C	$5V \pm 10\%$	3.5 to 24 MHz	

Note:

1. Operating ranges define those limits between which the functionality of the device is guaranteed.

 $(T_A = 0^{\circ}C \text{ to } 70^{\circ}C; V_{CC} = 5V \pm 10\%; G_{ND} = 0V)$

Symbol	Parameter	Test conditions	Min	Max	Unit
VIL	Input low voltage		-0.5	0.2Vcc - 0.1	V
VIL1	Input low voltage		-0.5	0.2Vcc - 0.3	V
Vih	Input high voltage (All except XTAL 1, RST)		0.2Vcc + 0.9	Vcc + 0.5	V
VIH1	Input high voltage (XTAL 1)		0.7Vcc	Vcc + 0.5	V
Vsc++	RST positive schmitt-trigger threshold voltage		0.7Vcc	Vcc + 0.5	V
Vsch-	RST negative schmitt-trigger threshold voltage		0	0.3Vcc	V
Vol ⁽¹⁾	Output low voltage	IoL = 100 μA		0.3	V
	(Ports 1, 2, and 3)	lo∟ = 1.6 mA		0.45	V
		lo∟ = 3.5 mA		1.0	V
Vol1 ⁽¹⁾	Output low voltage	IoL = 200 μA		0.3	V
	(Port 0, ALE, PSEN)	loL = 3.2 mA		0.45	V
		lo∟ = 7.0 mA		1.0	V
Vон	Output high voltage (Port 1, 2, 3, ALE, PSEN)	Іон = –10 μA Vcc = 4.5V-5.5V	0.9Vcc	—	V
		IoL = -25 μA	0.75Vcc		V
		IoL = -60 μA	2.4		V
Vон1	Output high voltage (Port 0, ALE, PSEN)	Іон = —80 μА Vcc = 4.5V-5.5V	0.9Vcc	—	V
		Іон = –300 μА	0.75Vcc		V
		Іон = -800 μА	2.4		V
lı∟	Logical 0 input current (Port 1, 2, 3)	VIN = 0.45V		-50	μΑ
lu	Input leakage current (Port 0)	0.45V < VIN < Vcc	-10	+10	μA
Ιτι	Logical 1-to-0 transition current (Port 1, 2, 3)	VIN = 2.0V	—	-650	μA
RRST	RST pulldown resister		50	300	Kohm

Note:

1. Under steady state (non-transient) conditions, lol must be externally limited as follows:

Maximum Io∟ per port pin: 10 mA

Maximum loL per 8-bit port

Port 0: 26 mA Port 1, 2, 3: 15 mA

Maximum total loL for all output pins: 71 mA

If IoL exceeds the test condition, VoL may exceed the related specification. Pins are not guaranteed to sink greater than the listed test conditions.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test conditions	Min	Max	Unit
lcc	Power supply current ⁽¹⁾				
	Active mode	12 MHz		20	mA
		16 MHz		26	mA
		20 MHz	—	32	mA
		24 MHz	—	38	mA
		32 MHz		50	mA
		40 MHz	—	62	mA
	Idle mode	12 MHz		5	mA
		16 MHz		6	mA
		20 MHz	—	7.6	mA
		24 MHz		9	mA
		32 MHz		12	mA
		40 MHz	—	15	mA
	Power-down mode			50	μA

Note:

1. See Figures 12, 13, 14, and 15 for Icc test conditiions.



Figure 12. Active Mode











Figure 15. Icc Test Conditions

Clock signal waveform for Icc tests in active and idle mode (tclch = tchcl = 5 ns)

AC CHARACTERISTICS

(T_A = 0°C to 70°C; Vcc = 5V \pm 10%; GND = 0V; C_L for Port 0, ALE and \overline{PSEN} ; Outputs = 100 pF; C_L for other outputs = 80 pF)

External Memory Characteristics

		24 N	/IHz	40 N	ЛНz			
		Clo	ck	Clo	ock	Variable (Dscillator	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Unit
1/tclcl	Oscillator frequency	_	_			3.5	40	MHz
t LHLL	ALE pulse width	43		10		2tclcl-40		ns
tavll	Address valid to ALE low	2	_	-15		tclcl-40		ns
tllax	Address hold after ALE low	7		-10		tclcl-35		ns
tlliv	ALE low to valid instr in		105		55		3tclcl-20	ns
t llpl	ALE low to PSEN low	2		-15		tclcl-40		ns
t PLPH	PSEN pulse width	80		30		3tclcl-45		ns
t PLIV	PSEN low to valid instr in		73		40		2tclcl-10	ns
t PXIX	Input instr hold after PSEN	0	_	0—		0		ns
t PXIZ	Input instr float after PSEN		73		40		2tclcl-10	ns
t AVIV	Address to valid instr in		147		80		4tclcl-20	ns
t PLAZ	PSEN low to address float		10		10		10	ns
t rlrh	RD pulse width	150		50		6tclcl-100		ns
twlwh	WR pulse width	150		50		6tclcl-100		ns
trldv	RD low to valid data in		114		30		5tclcl-95	ns
trhdx	Data hold after RD	0		0		0		ns
trhdz	Data float after RD		63		30	_	2tclcl-70	ns
t lldv	ALE low to valid data in		244		110	_	8tclcl-90	ns
tavdv	Address to valid data in		285		135	_	9tclcl-90	ns
tllwl	ALE low to \overline{RD} or \overline{WR} low	75	175	25	125	3tclcl-50	3tclcL+50	ns
tavwl	Address to RD or WR low	77		10		4tclcl-90		ns
t qvwx	Data valid to WR transition	2		-1.5		tclcl-40		ns
twнqx	Data hold after WR	2		-1.5		tclcl-40		ns
tqvwн	Data valid to WR high	219	_	105	_	7tclcl-70		ns
t RLAZ	RD low to address float		63		30		2tclcl-20	ns
twhlh	\overline{RD} or \overline{WR} high to ALE high	2	82	-15	65	tclcl-40	tclcl+40	ns

Serial Port Timing: Shift Register Mode

		24 N	/Hz	40 N	/Hz	Variable	Oscillator	
Symbol	Parameter	Min	Max	Min	Max	Min	Max	Unit
txlxl	Serial port clock cycle time	500				12tclcl		ns
t qvxh	Output data setup to clock rising edge	284	_	117	_	10tclcl-133		ns
tхнох	Output data hold after clock rising edge	33	_	0	—	2tclcl-50		ns
t xhdx	Input data hold after clock rising edge	0	_	0	_	0	—	ns
t XHDV	Clock rising edge to input data valid		284		117	_	10tclcl-133	ns

External Clock Drive

Symbol	Parameter	Min	Max	Unit
1/tclcl	Oscillator Frequency	3.5	24	MHz
tснсх	High time	10	—	ns
tcLcx	Low time	10	—	ns
tсьсн	Rise time	—	10	ns
t CHCL	Fall time		10	ns

ROM Verification Characteristics

Symbol	Parameter	Min	Max	Unit
1/tclcl	Oscillator Frequency	2.5	40	MHz
t AVQV	Address to data valid		48tclcl	
t ELQV	ENABLE low to data valid	—	48tclcl	
t ehqz	Data float after ENABLE	0	48tclcl	

TIMING WAVEFORMS



Figure 16. External Program Memory Read Cycle



Figure 17. External Data Memory Read Cycle



Figure 18. External Data Memory Write Cycle



Figure 19. Shift Register Mode Timing Waveforms







Figure 21. ROM Verification Waveforms



Figure 22. AC Test Point

Note:

1. AC inputs during testing are driven at VCC - 0.5V for logic "1" and 0.45V for logic "0". Timing measurements are made at V_{IH} min for logic "1" and max for logic "0".

Speed	Order Part Number	Package
12 MHz	IS80C52-12PL IS80C52-12PQ IS80C52-12W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
20 MHz	IS80C52-20PL IS80C52-20PQ IS80C52-20W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
24 MHz	IS80C52-24PL IS80C52-24PQ IS80C52-24W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
40 MHz	IS80C52-40PL IS80C52-40PQ IS80C52-40W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
12 MHz	IS80C32-12PL IS80C32-12PQ IS80C32-12W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
20 MHz	IS80C32-20PL IS80C32-20PQ IS80C32-20W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
24 MHz	IS80C32-24PL IS80C32-24PQ IS80C32-24W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP
40 MHz	IS80C32-40PL IS80C32-40PQ IS80C32-40W	PLCC – Plastic Leaded Chip Carrier PQFP - Plastic Qual Flat Pack 600-mil Plastic DIP

ORDERING INFORMATION



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